

## Features

- GaN on SiC Depletion-Mode Transistor Technology
- Internally Matched
- Common-Source Configuration
- Broadband Class AB Operation
- 50 V Operation
- 800 W performance at 20 $\mu$ s and 6% duty factor
- RoHS\* Compliant and 260°C Reflow Compatible
- MTTF = 600 years ( $T_J < 200^\circ\text{C}$ )

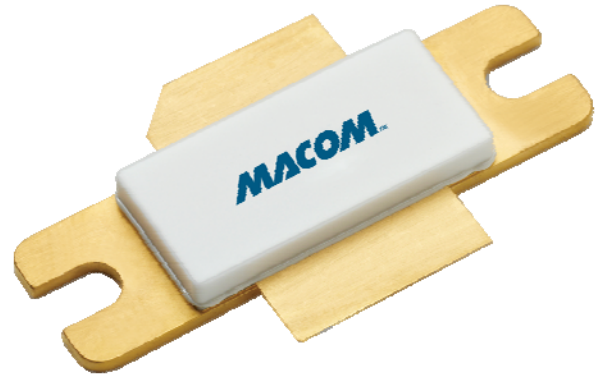
## Applications

- L-Band pulsed radar.

## Description

The MAGX-000912-650L00 and MAGX-000912-650L0S (MAGX-000912-650L0x) are gold metalized matched gallium nitride (GaN) on silicon carbide RF power transistor optimized for civilian and military pulsed avionics amplifier applications for the 960 MHz to 1215 MHz range such as Mode-S, TCAS, JTIDS, DME and TACAN. Using state of the art wafer fabrication processes, these high performance transistors provide high gain, efficiency, bandwidth, ruggedness over a wide bandwidth for today's demanding application needs. High breakdown voltages allow for reliable and stable operation in extreme mismatched load conditions unparalleled with older semiconductor technologies.

## MAGX-000912-650L00



## MAGX-000912-650L0S



## Ordering Information

Part Number	Description
MAGX-000912-650L00	Standard Flange
MAGX-000912-650L0S	Earless Flange
MAGX-A00912-650L00	960 - 1215 MHz Evaluation Board

1. When ordering the evaluation board, please indicate on sales order notes if it will be used for:
  - A. Standard Flange devices
  - B. Earless Flange devices

\* Restrictions on Hazardous Substances, European Union Directive 2011/65/EU.

**GaN on SiC HEMT Pulsed Power Transistor**  
**650 W Peak, 960-1215 MHz, 128  $\mu$ s Pulse, 10% Duty**

Rev. V2

**Typical RF Performance: (under standard operating conditions),  $P_{OUT} = 650$  W (Peak)**

Freq (MHz)	$P_{IN}$ (W)	Gain (dB)	$I_D$ (A)	Eff. (%)	RL (dB)	Droop (dB)	+1dB OD (W)	VSWR-S (3:1)	VSWR-T (3:1)
960	6.5	20	21	62	-8	0.3	740	S	P
1030	5.2	21	20.3	64	-13	0.2	723	S	P
1090	5.8	20.5	20.3	64	-11	0.3	719	S	P
1150	5.7	20.6	21	62	-15	0.3	720	S	P
1215	6.0	20.4	21.6	60	-11	0.2	718	S	P

**Electrical Specifications: Freq. = 960 - 1215 MHz,  $T_A = 25^\circ\text{C}$**

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Units
<b>RF Functional Tests: <math>V_{DD} = 50</math> V; <math>I_{DQ} = 500</math> mA; Pulse = 128 <math>\mu</math>s / 10%</b>						
Input Power	$P_{OUT} = 650$ W Peak (65 W avg.)	$P_{IN}$	-	5.8	9.2	Wpk
Power Gain	$P_{OUT} = 650$ W Peak (65 W avg.)	$G_P$	18.5	20.5	-	dB
Drain Efficiency	$P_{OUT} = 650$ W Peak (65 W avg.)	$\eta_D$	57	62	-	%
Pulse Droop	$P_{OUT} = 650$ W Peak (65 W avg.)	Droop	-	0.3	0.5	dB
Load Mismatch Stability	$P_{OUT} = 650$ W Peak (65 W avg.)	VSWR-S	-	3:1	-	-
Load Mismatch Tolerance	$P_{OUT} = 650$ W Peak (65 W avg.)	VSWR-T	-	3:1	-	-

**Electrical Characteristics:  $T_A = 25^\circ\text{C}$**

Parameter	Test Conditions	Symbol	Typ.	Units
<b>DC Characteristics</b>				
Drain-Source Leakage Current	$V_{GS} = -8$ V, $V_{DS} = 175$ V	$I_{DS}$	1.7	mA
Gate Threshold Voltage	$V_{DS} = 5$ V, $I_D = 90$ mA	$V_{GS(TH)}$	-3.1	V
Forward Transconductance	$V_{DS} = 5$ V, $I_D = 21$ mA	$G_M$	22	S
<b>Dynamic Characteristics</b>				
Input Capacitance	Not applicable - Input matched	$C_{ISS}$	N/A	pF
Output Capacitance	$V_{DS} = 50$ V, $V_{GS} = -8$ V, $F = 1$ MHz	$C_{OSS}$	55	pF
Reverse Transfer Capacitance	$V_{DS} = 50$ V, $V_{GS} = -8$ V, $F = 1$ MHz	$C_{RSS}$	5.5	pF

## GaN on SiC HEMT Pulsed Power Transistor 650 W Peak, 960-1215 MHz, 128 $\mu$ s Pulse, 10% Duty

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### Absolute Maximum Ratings<sup>2,3,4,5</sup>

Parameter	Rating
Supply Voltage ( $V_{DD}$ )	+65 V
Supply Voltage ( $V_{GS}$ )	-8 to -2 V
Supply Current ( $I_D$ )	33 A
Input Power ( $P_{IN}$ )	$P_{IN}$ (nominal) +3 dB
Junction/Channel Temp	200°C
Pulsed Power Dissipation at +85°C	1 kW
Thermal Resistance, ( $T_J = +70^\circ\text{C}$ ) $V_{DD} = 50\text{ V}$ , $I_{DQ} = 500\text{ mA}$ , $P_{OUT} = 650\text{ W}$ , 128 $\mu$ s Pulse / 10% Duty	0.17°C/W
Operating Temperature	-40 to +95°C
Storage Temperature	-65 to +150°C
Mounting Temperature	See solder reflow profile
ESD Min. - Charged Device Model (CDM)	1300 V
ESD Min. - Human Body Model (HBM)	4000 V

- Operation of this device above any one of these parameters may cause permanent damage.
- Input Power Limit is +3 dB over nominal drive required to achieve  $P_{OUT} = 650\text{ W}$ .
- Channel temperature directly affects a device's MTTF. Channel temperature should be kept as low as possible to maximize lifetime.
- For saturated performance it recommended that the sum of  $(3 \cdot V_{DD} + \text{abs}(V_{GG})) < 175\text{ V}$ .

### Test Fixture Impedances

F (MHz)	$Z_{IF}$ ( $\Omega$ )	$Z_{OF}$ ( $\Omega$ )
960	0.7 - j0.9	1.4 + j0.7
1030	0.7 - j0.5	1.7 + j0.6
1060	0.8 - j0.1	1.7 + j0.5
1150	0.9 + j0.1	1.6 + j0.3
1215	1.1 + j0.4	1.2 + j0.4

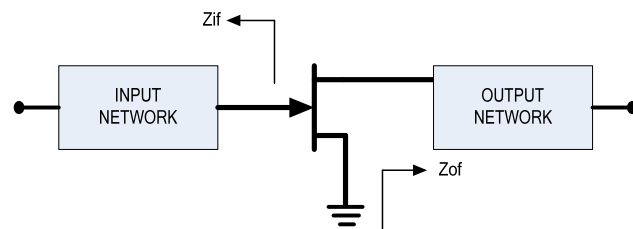
### Correct Device Sequencing

#### Turning the device ON

- Set  $V_{GS}$  to the pinch-off ( $V_P$ ), typically -5 V.
- Turn on  $V_{DS}$  to nominal voltage (50 V).
- Increase  $V_{GS}$  until the  $I_{DS}$  current is reached.
- Apply RF power to desired level.

#### Turning the device OFF

- Turn the RF power off.
- Decrease  $V_{GS}$  down to  $V_P$ .
- Decrease  $V_{DS}$  down to 0 V.
- Turn off  $V_{GS}$ .



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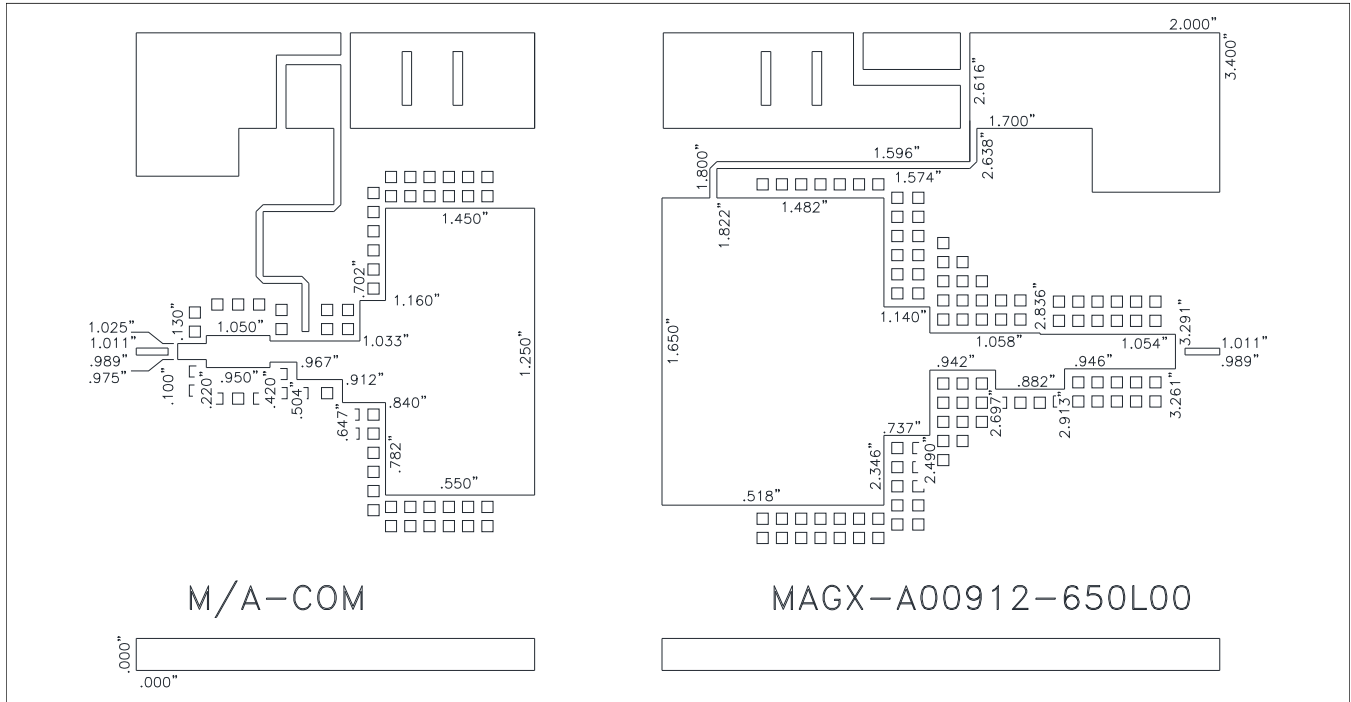
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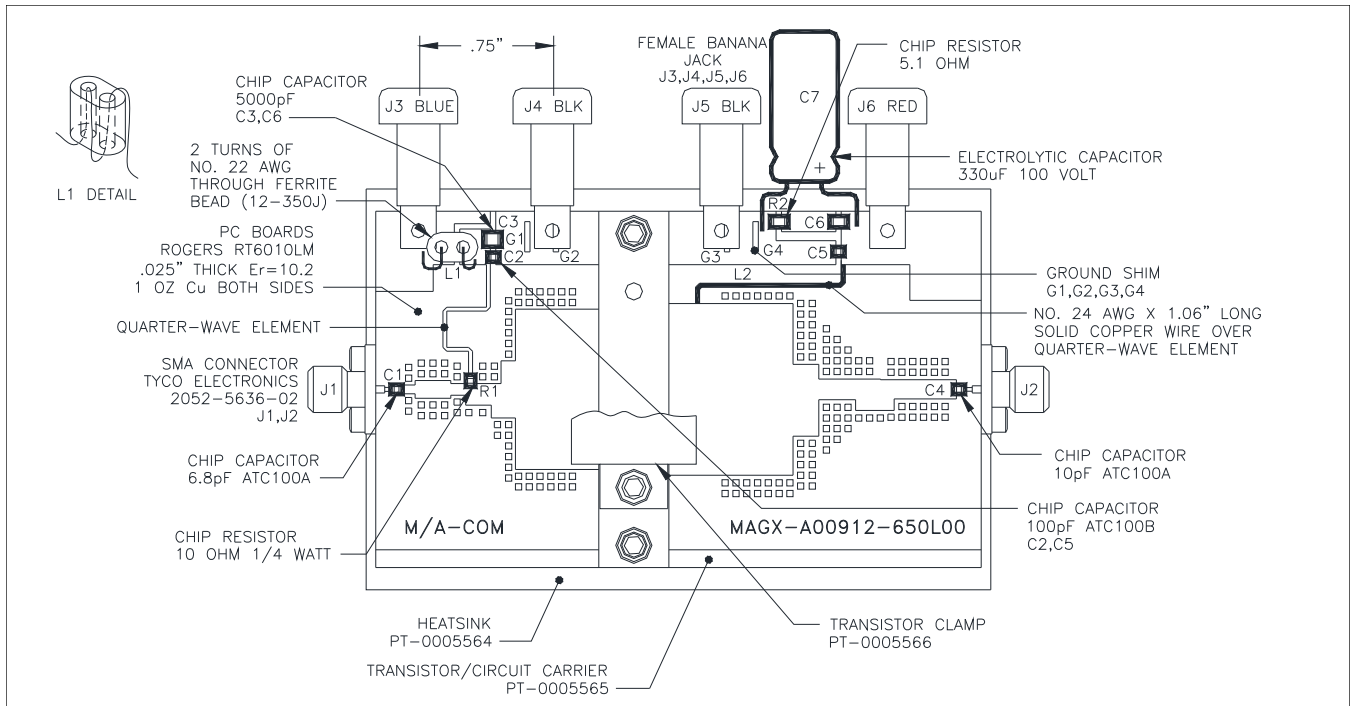
**GaN on SiC HEMT Pulsed Power Transistor**  
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## Test Fixture Circuit Dimensions

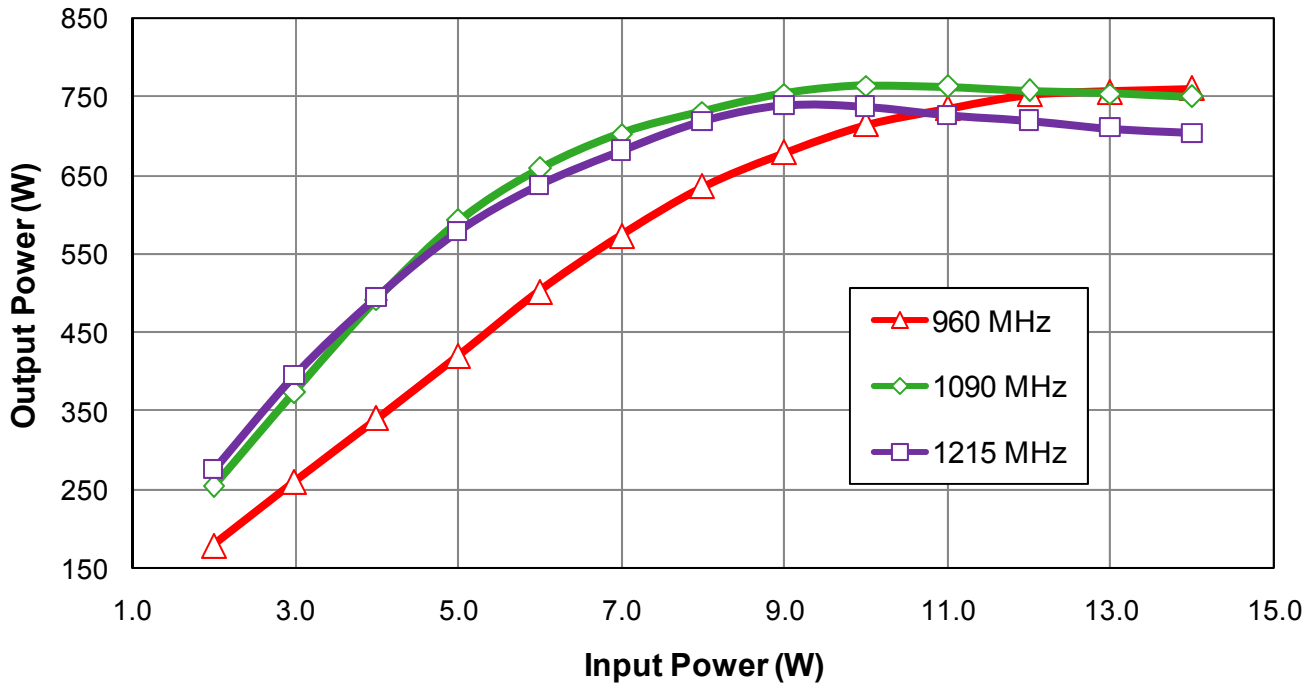


## Test Fixture Assembly

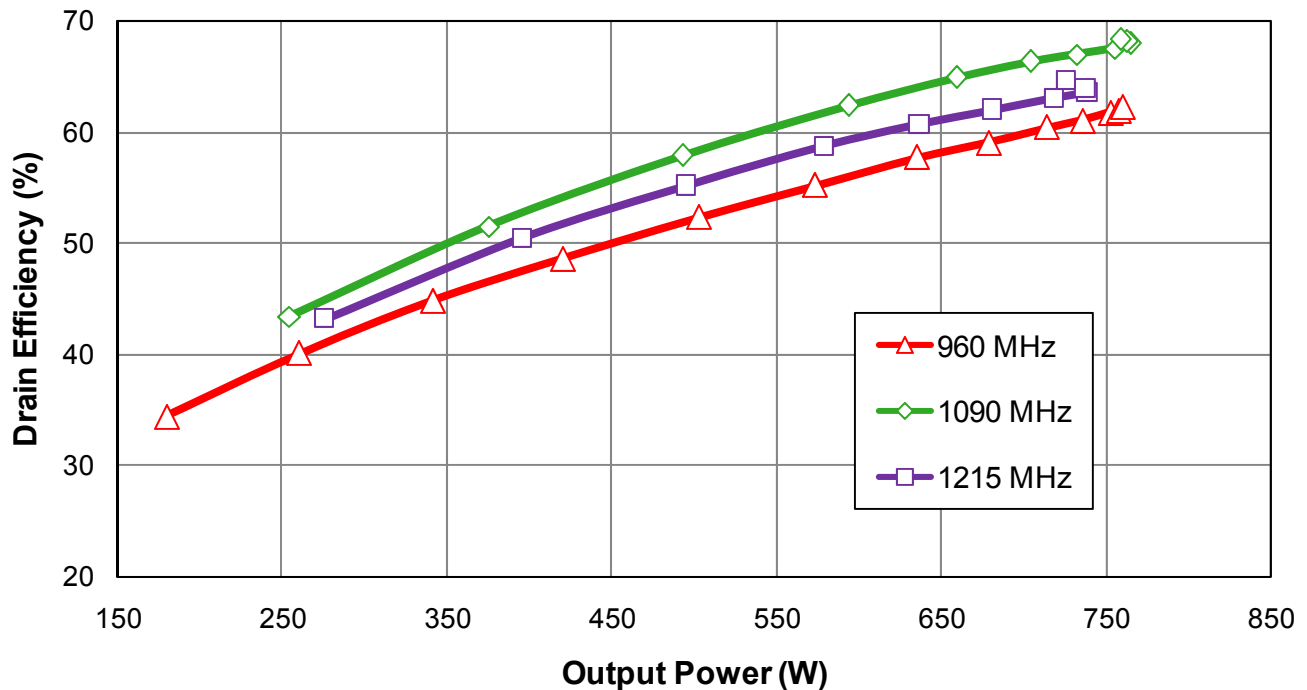


Contact factory for gerber file or additional circuit information.

RF Power Transfer Curve (Output Power vs. Input Power)



RF Power Transfer Curve (Drain Efficiency vs. Output Power)



**Typical RF Performance under Alternate Operating Conditions<sup>6,7</sup>**  
 **$V_{DD} = 55$  V;  $I_{DQ} = 500$  mA; Pulse = 20  $\mu$ s / 6% ,  $P_{OUT} = 800$  W (Peak)**

Freq (MHz)	$P_{IN}$ (W)	Gain (dB)	$I_D$ (A)	Eff. (%)	RL (dB)	Droop (dB)	+1dB OD (W)	VSWR-S (3:1)	VSWR-T (3:1)
1025	7.5	20.3	22.3	65.4	-11	0.1	875	S	P
1090	7.3	20.4	22.5	64.4	-11	0.1	872	S	P
1150	6.9	20.7	23.4	61.9	-14	0.1	875	S	P

**RF Performance (Alternate Operating Conditions<sup>6,7</sup>): Freq. = 1025 - 1150 MHz,  $T_A = 25^\circ$ C**

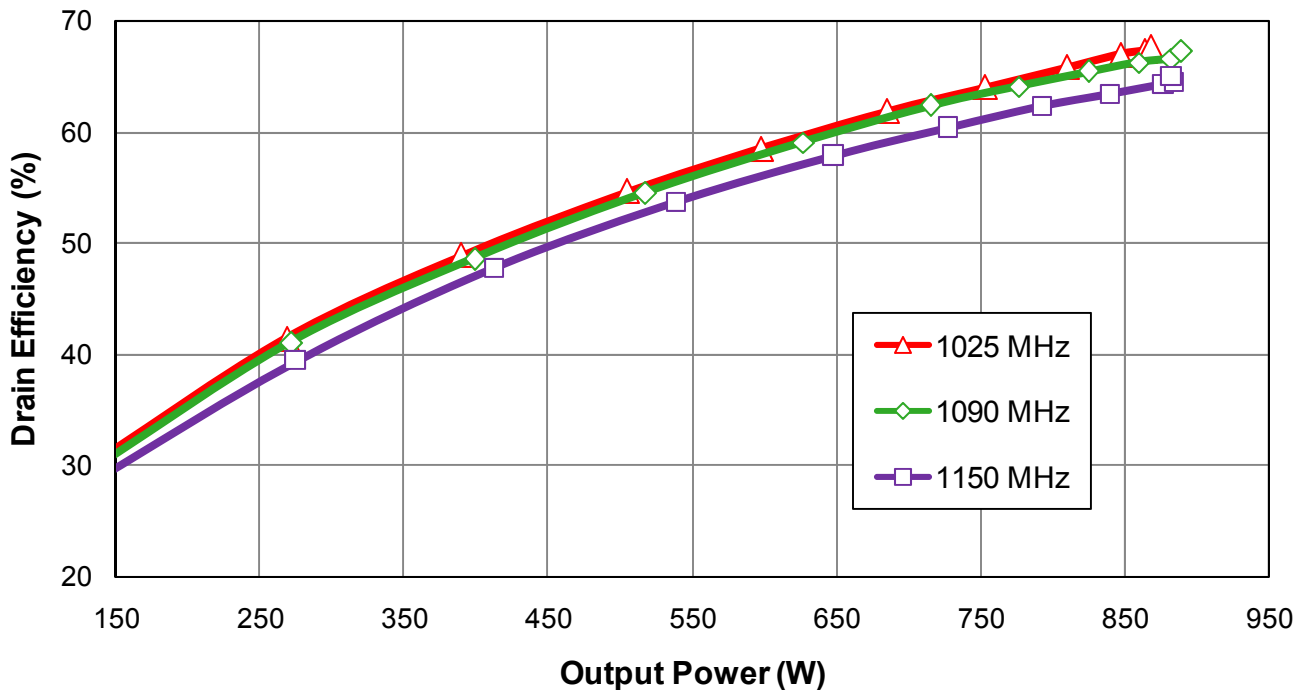
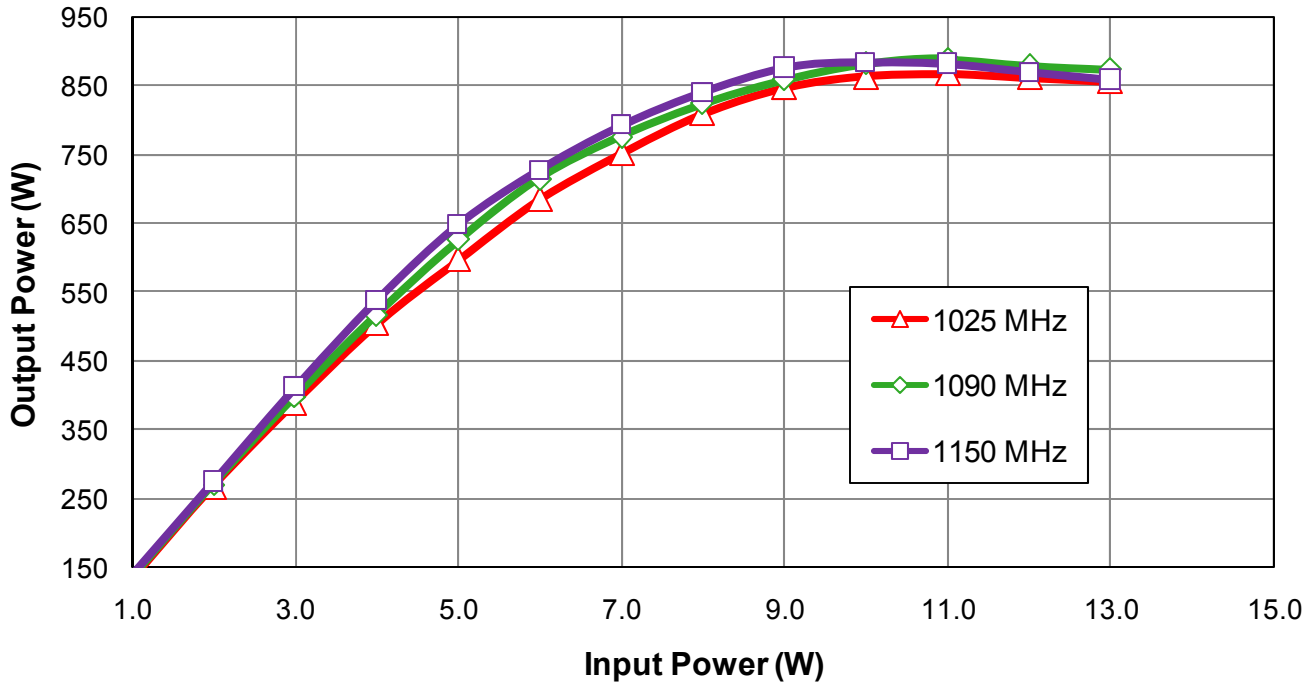
Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Units
<b>RF Functional Tests: <math>V_{DD} = 55</math> V; <math>I_{DQ} = 500</math> mA; Pulse = 20 <math>\mu</math>s / 6%</b>						
Input Power	$P_{OUT} = 800$ W Peak (48 W avg.)	$P_{IN}$	-	7.2	-	Wpk
Power Gain	$P_{OUT} = 800$ W Peak (48 W avg.)	$G_P$	-	20.4	-	dB
Drain Efficiency	$P_{OUT} = 800$ W Peak (48 W avg.)	$\eta_D$	-	63	-	%
Pulse Droop	$P_{OUT} = 800$ W Peak (48 W avg.)	Droop	-	0.1	-	dB
Load Mismatch Stability	$P_{OUT} = 800$ W Peak (48 W avg.)	VSWR-S	-	3:1	-	-
Load Mismatch Tolerance	$P_{OUT} = 800$ W Peak (48 W avg.)	VSWR-T	-	3:1	-	-

6. Operation of this device above  $V_{DD} = 50$ V may decrease operational lifetime.  
 7. Data measured in standard RF test fixture, reference page 4.

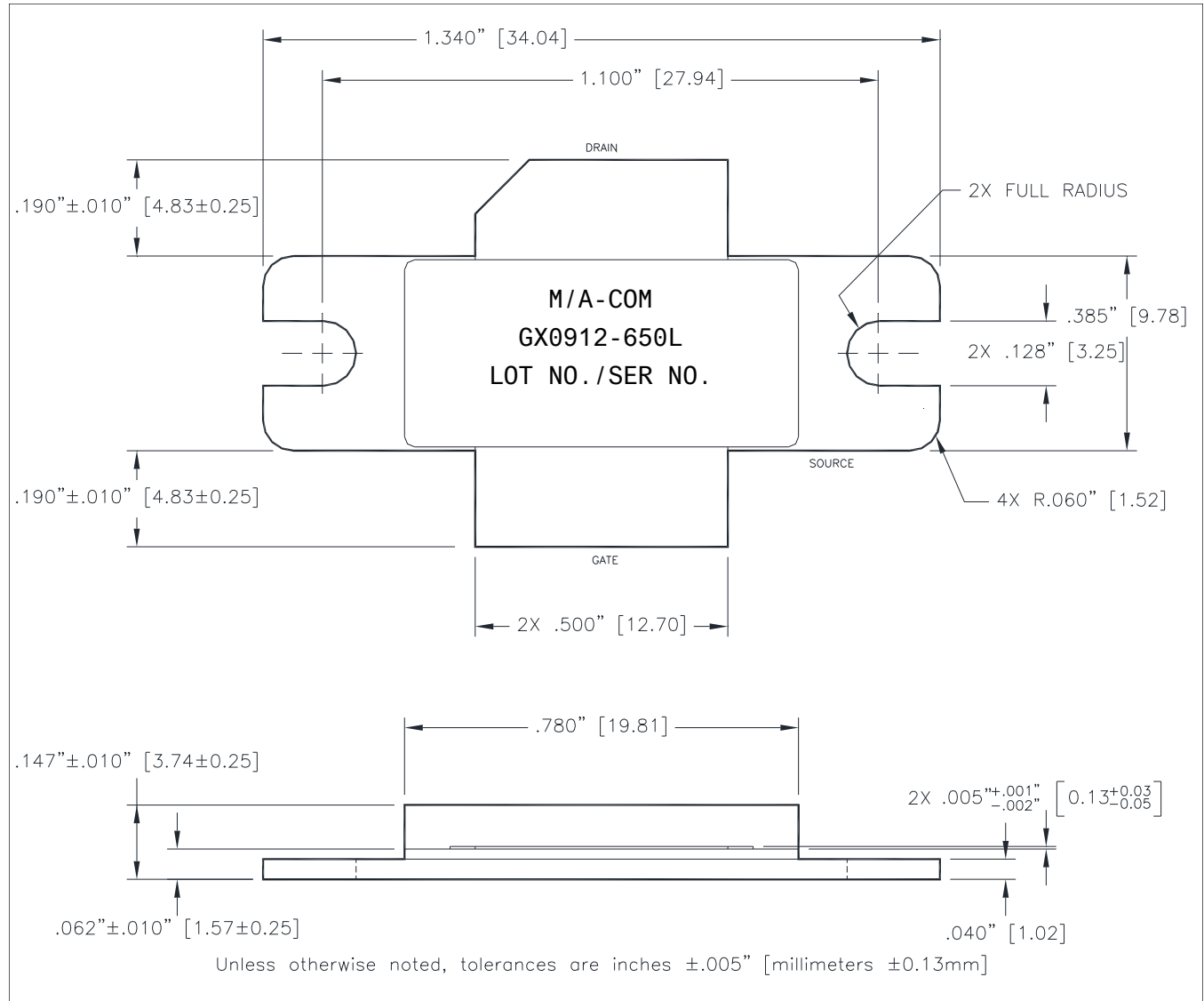
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RF Power Transfer Curves under Alternate Operating Conditions<sup>6,7</sup>  
 ( $V_{DD} = 55$  V;  $I_{DQ} = 500$  mA; Pulse = 20  $\mu$ s / 6%)



## Outline Drawing MAGX-000912-650L00





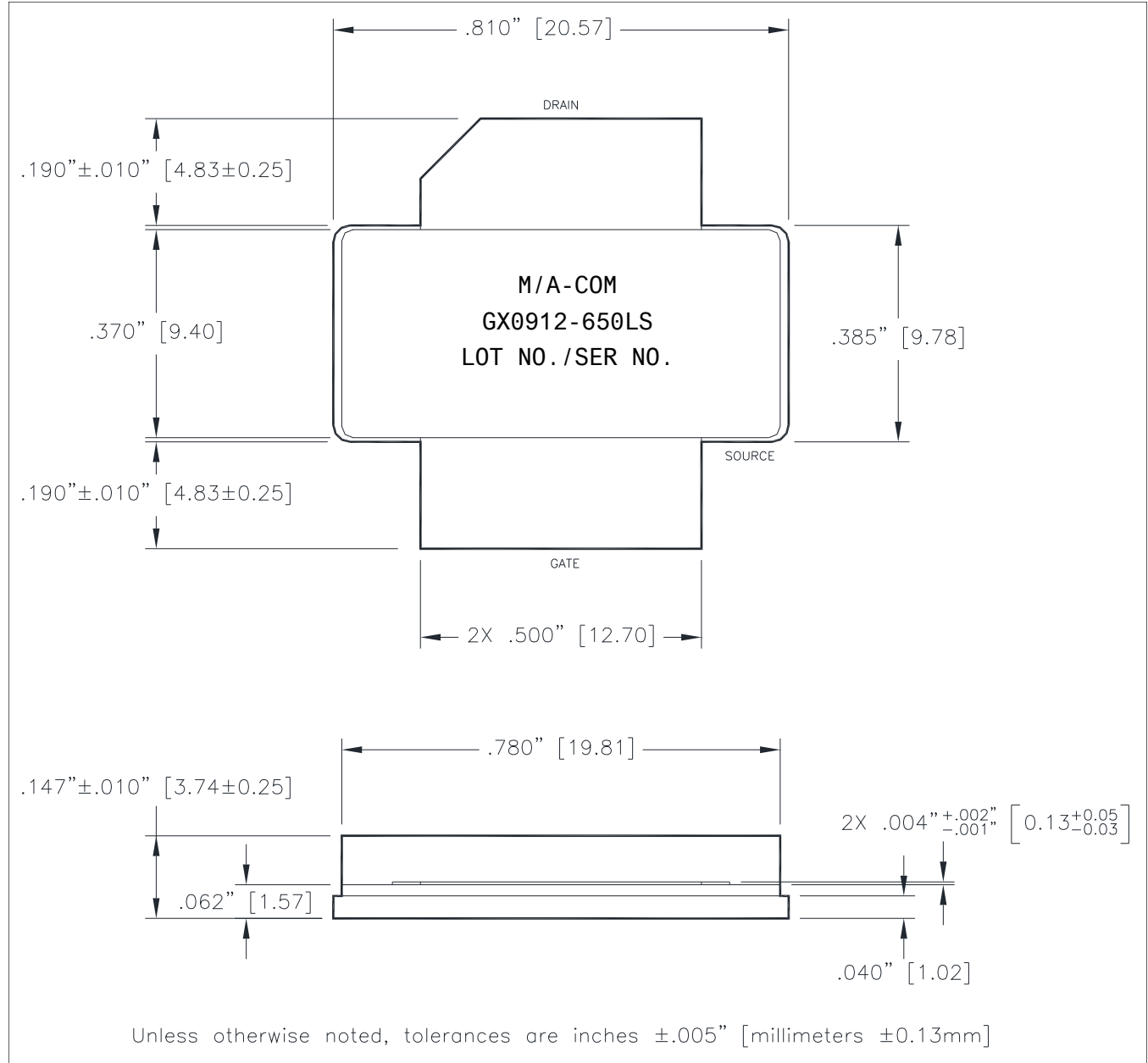
# MAGX-000912-650L0x



GaN on SiC HEMT Pulsed Power Transistor  
650 W Peak, 960-1215 MHz, 128  $\mu$ s Pulse, 10% Duty

Rev. V2

## Outline Drawing MAGX-000912-650L0S



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